proposed (Patent Literatures 1 to 6).

Citation List

Patent Literature

[0004]

Patent Literature 1: JP H07-188362 A

Patent Literature 2: JP 2004-83680 A

Patent Literature 3: JP 3414556 B2

Patent Literature 4: JP 2003-306591 A

Patent Literature 5: JP 5649773 B2

Patent Literature 6: JP 2017-200997 A

Summary

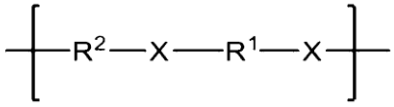
[0004a]

In an aspect of the present disclosure, there is provided a polymer comprising:

a repeating structural unit represented by the following Formula (1); and

a group Y represented by the following Formula (a) at a terminal:

[Chem. 1]



(1)

wherein X's are each independently -O-, -S-, or -

$N(R^3)$-, R^3 is a hydrogen atom, a monovalent hydrocarbon group having 1 to 20 carbon atoms, a monovalent halogenated hydrocarbon group having 1 to 20 carbon atoms, or a group obtained by substituting a part of the hydrocarbon group or the halogenated hydrocarbon group with at least one selected from an oxygen atom and a sulfur atom, R^1 is a divalent organic group, and R^2 is a divalent unsubstituted or substituted nitrogen-containing heteroaromatic ring;

[Chem. 2]

$$-Y \quad (a)$$

wherein Y is a group containing an ethylenically unsaturated double bond and having 3 to 50 carbon atoms, an unsubstituted or substituted aromatic hydrocarbon group having 6 to 50 carbon atoms, an unsubstituted or substituted aliphatic hydrocarbon group having 6 to 50 carbon atoms, or an unsubstituted nitrogen-containing heteroaromatic ring, and when the aromatic hydrocarbon group or the aliphatic hydrocarbon group has a substituent, the substituent is a group other than a hydroxy group.

[0004b]

In another aspect of the present disclosure, there is provided a composition comprising:

the polymer as disclosed herein; and

a curable compound (B) other than the polymer.

[0004c]

In a further aspect of the present disclosure, there is provided a cured product which is a cured product of the composition as disclosed herein.

[0004d]

In another aspect of the present disclosure, there is provided a laminate comprising:

a substrate; and

a cured layer formed using the composition as disclosed herein.

[0004e]

In a further aspect of the present disclosure, there is provided an electronic component comprising the cured product as disclosed herein or the laminate as disclosed herein.

Technical Problem

[0005]

However, the conventional materials such as the compositions described in Patent Literatures 1 to 6 are excellent in low dielectric-low loss tangent to some extent, but do not necessarily satisfy all requirements for properties required for electronic materials such as heat resistance, chemical resistance, and adhesiveness.

For example, a composition using a polyphenylene ether

resin and a fluororesin are excellent in low dielectric-low loss tangent and heat resistance, but do not have sufficient